## **Chip Monolithic Ceramic Capacitors**

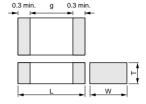


## Only for Information Devices/Tip & Ring

#### ■ Features

- 1. These items are designed specifically for telecommunication devices (IEEE802.3) in Ethernet LAN.
- 2. A new monolithic structure for small, high capacitance capable of operating at high voltage levels
- 3. Sn-plated external electrodes realizes good solderability.
- 4. Only for reflow soldering.
- 5. The low-profile type (thickness: 1.5mm max.) is available. Fit for use on thinner type equipment.

# 222



Part Number	Dimensions (mm)				
Part Number	L	W	T	g min.	
GR442Q	4.5 ±0.3	2.0 ±0.2	1.5 +0, -0.3	2.5	
GR443D	4.5 ±0.4	3.2 ±0.3	2.0 +0, -0.3	2.2*	
GR443Q	4.5 ±0.4	3.2 ±0.3	1.5 +0, -0.3	2.5	

<sup>\*</sup> GR443DR73D : 2.5mm min.

#### ■ Applications

Ideal for use on telecommunication devices in Ethernet LAN.

Part Number	Rated Voltage (V)	TC Code (Standard)	Capacitance (pF)	Length L (mm)	Width W (mm)	Thickness T (mm)	Electrode g min. (mm)	Electrode e (mm)
GR442QR73D101KW01L	DC2000	X7R (EIA)	100 ±10%	4.5	2.0	1.5	2.5	0.3 min.
GR442QR73D121KW01L	DC2000	X7R (EIA)	120 ±10%	4.5	2.0	1.5	2.5	0.3 min.
GR442QR73D151KW01L	DC2000	X7R (EIA)	150 ±10%	4.5	2.0	1.5	2.5	0.3 min.
GR442QR73D181KW01L	DC2000	X7R (EIA)	180 ±10%	4.5	2.0	1.5	2.5	0.3 min.
GR442QR73D221KW01L	DC2000	X7R (EIA)	220 ±10%	4.5	2.0	1.5	2.5	0.3 min.
GR442QR73D271KW01L	DC2000	X7R (EIA)	270 ±10%	4.5	2.0	1.5	2.5	0.3 min.
GR442QR73D331KW01L	DC2000	X7R (EIA)	330 ±10%	4.5	2.0	1.5	2.5	0.3 min.
GR442QR73D391KW01L	DC2000	X7R (EIA)	390 ±10%	4.5	2.0	1.5	2.5	0.3 min.
GR442QR73D471KW01L	DC2000	X7R (EIA)	470 ±10%	4.5	2.0	1.5	2.5	0.3 min.
GR442QR73D561KW01L	DC2000	X7R (EIA)	560 ±10%	4.5	2.0	1.5	2.5	0.3 min.
GR442QR73D681KW01L	DC2000	X7R (EIA)	680 ±10%	4.5	2.0	1.5	2.5	0.3 min.
GR442QR73D821KW01L	DC2000	X7R (EIA)	820 ±10%	4.5	2.0	1.5	2.5	0.3 min.
GR442QR73D102KW01L	DC2000	X7R (EIA)	1000 ±10%	4.5	2.0	1.5	2.5	0.3 min.
GR442QR73D122KW01L	DC2000	X7R (EIA)	1200 ±10%	4.5	2.0	1.5	2.5	0.3 min.
GR442QR73D152KW01L	DC2000	X7R (EIA)	1500 ±10%	4.5	2.0	1.5	2.5	0.3 min.
GR443QR73D182KW01L	DC2000	X7R (EIA)	1800 ±10%	4.5	3.2	1.5	2.5	0.3 min.
GR443QR73D222KW01L	DC2000	X7R (EIA)	2200 ±10%	4.5	3.2	1.5	2.5	0.3 min.
GR443QR73D272KW01L	DC2000	X7R (EIA)	2700 ±10%	4.5	3.2	1.5	2.5	0.3 min.
GR443QR73D332KW01L	DC2000	X7R (EIA)	3300 ±10%	4.5	3.2	1.5	2.5	0.3 min.
GR443QR73D392KW01L	DC2000	X7R (EIA)	3900 ±10%	4.5	3.2	1.5	2.5	0.3 min.
GR443DR73D472KW01L	DC2000	X7R (EIA)	4700 ±10%	4.5	3.2	2.0	2.5	0.3 min.

## **Specifications and Test Methods**

No.	o. Item		Specifications				
1	Operating −55 to +125°C		-				
2	Appearar	Appearance No defects or abnormalities		Visual inspection			
3	Dimensio	ns	Within the specified dimensions	Using calipers			
4	Dielectric Strength		No defects or abnormalities	No failure should be observed when voltage in table is applied between the terminations, provided the charge/discharge current is less than 50mA.			
7				Rated voltage	Test Voltage	Time	
				DC2kV	120% of the rated voltage AC1500V (r.m.s.)	60±1 sec. 60±1 sec.	
5	Pulse Voltage (Application : DC2kV item)		No self healing break downs or flash-overs have taken place in the capacitor.	10 impulse of alternating polarity is subjected. (5 impulse for each polarity) The interval between impulse is 60 sec. Applied Voltage: 2.5kV zero to peak			
6	Insulation I	Resistance	More than $6{,}000M\Omega$	The insulation resistance should be measured with DC500= and within 60±5 sec. of charging.			
7	Capacitance		Within the specified tolerance	The capacitance/D.F. should be measured at 25℃ at a frequency of 1±0.2kHz and a voltage of AC1±0.2V (r.m.s.)  •Pretreatment			
8	Dissipation Factor (D.F.)		0.025 max.	Perform a heat treatment at $150^{+0}_{-10}$ °C for $60\pm5$ min. and then let sit for $24\pm2$ hrs. at *room condition.			
9	Capacitance Temperature Characteristics		Cap. Change within ±15% (Temp. Range : −55 to +125℃)	The range of capacitance change compared with the 25°C value within the specified range.  •Pretreatment  Perform a heat treatment at 150±00°C for 60±5 min. and then let sit for 24±2 hrs. at *room condition.			
10	O Adhesive Strength of Termination		No removal of the terminations or other defect should occur.	Solder the capacitor to the testing jig (glass epoxy board) sho in Fig. 1 using a eutectic solder.  Then apply 10N force in the direction of the arrow.  The soldering should be done either with an iron or using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock.  10N, 10±1s Speed: 1.0mm/s Glass Epoxy Board  Fig. 1		or using the so that the eat shock.	
		Appearance	No defects or abnormalities	Solder the capacitor	to the test jig (glass epoxy bo	aard)	
		Capacitance	Within the specified tolerance	The capacitor should	d be subjected to a simple har	monic motion	
11	Vibration Resistance D.F.	·	0.025 max.	uniformly between the frequency range, from traversed in approxition of 2 hrs. (total of 6 hrs.).	tude of 1.5mm, the frequency he approximate limits of 10 an mon 10 to 55Hz and return to 10 mately 1 min. This motion shows in each 3 mutually perpendice to 10 materials and 10	d 55Hz. The DHz, should be uld be applied ular directions	

<sup>\* &</sup>quot;Room condition" Temperature : 15 to 35°C, Relative humidity : 45 to 75%, Atmospheric pressure : 86 to 106kPa

Continued on the following page.





## **Specifications and Test Methods**

Continued from the preceding page

	Continued fr	om the pred	eding page.	7			
No.	Ite	em	Specifications	Test Method			
12	12 Deflection		No cracking or marking defects should occur.	Solder the capacitor to the testing jig (glass epoxy board) shi in Fig. 2 using a eutectic solder.  Then apply a force in the direction shown in Fig. 3.  The soldering should be done either with an iron or using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock.  20 50 Pressurizing speed:1.0mm/s Pressurize Pressurize  10 Flexure=1  11 Flexure=1  12 Flexure=1  13 Flexure=1  14 Flexure=1			
13	Solderability of Termination 75% of the terminations are to be soldered evenly and continuously.			Immerse the capacitor in a solution of ethanol (JIS-K-8101) and rosin (JIS-K-5902) (25% rosin in weight proportion).  Immerse in eutectic solder solution for 2±0.5 sec. at 235±5°C.  Immersing speed: 25±2.5mm/s			
		Appearance	No marking defects	Preheat the capacitor at 120 to 150°C* for 1 min.  Immerse the capacitor in eutectic solder solution at 260±5°C for 10±1 sec. Let sit at *room condition for 24±2 hrs., then measure.  •Immersing speed: 25±2.5mm/s  •Pretreatment			
	Resistance	Capacitance Change D.F.	Within ±10%  0.025 max.				
		I.R.	More than 1.000M $\Omega$	Perform a heat treatment at 150± <sub>1</sub> 8 °C for 60±5 min. and then			
14	to Soldering	I.K.	Wore than 1,000Ws2	let sit for 24±2 hrs. at *room condition.			
	Heat	Dielectric Strength	In accordance with item No.4	Step         Temperature         Time           1         100℃ to 120℃         1 min.           2         170℃ to 200℃         1 min.			
		Appearance	No marking defects	Fix the capacitor to the supporting jig (glass epoxy board) shown			
		Capacitance Change	Within ±15%	in Fig. 4 using a eutectic solder.  Perform the 5 cycles according to the 4 heat treatments listed in the following table.			
		D.F.	0.05 max.	Let sit for 24±2 hrs. at *room condition, then measure.			
		I.R.	More than $3,000 \text{M}\Omega$	Step Temperature (°C) Time (min.)			
				1 Min. Operating Temp.±3 30±3 2 Room Temp. 2 to 3			
				3 Max. Operating Temp.±2 30±3			
	Tomporaturo			4 Room Temp. 2 to 3			
15	Temperature Cycle	Dielectric Strength	In accordance with item No.4	Perform a heat treatment at 150 ± 18 °C for 60±5 min. and then let sit for 24±2 hrs. at *room condition.  Solder resist  Glass Epoxy Board  Fig. 4			
		Appearance	No marking defects				
	Humidity	Capacitance Change	Within ±15%	Let the capacitor sit at 40±2°C and relative humidity of 90 to 95% for 500±20 hrs.  Remove and let sit for 24±2 hrs. at *room condition, then			
16	,	D.F.	0.05 max.	measure.			
	State)	I.R.	More than 1,000M $\Omega$	•Pretreatment  Perform a heat treatment at 150 ± 18 ℃ for 60±5 min. and then let sit for 24±2 hrs. at *room condition.			
		Dielectric Strength	In accordance with item No.4				

<sup>\* &</sup>quot;Room condition" Temperature : 15 to 35°C, Relative humidity : 45 to 75%, Atmospheric pressure : 86 to 106kPa

Continued on the following page.





## **Specifications and Test Methods**

Continued from the preceding page.

No.	. Item		Specifications	Test Method
	Life	Appearance	No marking defects	
		Capacitance Change	Within ±20%	Apply 110% of the rated voltage for 1,000 ± 48 hrs. at maximum operating temperature ±3°C. Remove and let sit for 24 ±2 hrs. at *room condition, then measure.
17		D.F.	0.05 max.	The charge/discharge current is less than 50mA.
		I.R.	More than $2,000 \text{M}\Omega$	Pretreatment     Apply test voltage for 60±5 min. at test temperature.
		Dielectric Strength	In accordance with item No.4	Remove and let sit for 24±2 hrs. at *room condition.
	Humidity Loading (Applicat ion: DC250V item)	Appearance	No marking defects	
		Capacitance Change	Within ±15%	Apply the rated voltage at 40±2°C and relative humidity of 90 to 95% for 500±26 hrs.  Remove and let sit for 24±2 hrs. at *room condition, then
18		D.F.	0.05 max.	measure.
		I.R.	More than 10MΩ • μF	Pretreatment     Apply test voltage for 60±5 min. at test temperature.
		Dielectric Strength	In accordance with item No.4	Remove and let sit for 24±2 hrs. at *room condition.

<sup>\* &</sup>quot;Room condition" Temperature : 15 to 35°C, Relative humidity : 45 to 75%, Atmospheric pressure : 86 to 106kPa